

thin film device layers being deposited by a transfer method including a separation in a separable layer on which the at least one thin film device layer is formed.

3. (Twice Amended) The three-dimensional device according to claim 1, further comprising a first substrate, the transfer method comprising forming the at least one thin film device layer on a second substrate with the separable layer therebetween, and irradiating the separable layer with light to cause a separation in at least one of the separable layer and at an interface so that the at least one thin film device layer on the second substrate is transferred to the first substrate of the three-dimensional device.

Please add new claims 21-25 as follows:

--21. (New) A method of transferring a three-dimensional device having a plurality of thin film device layers to a first substrate, comprising:

forming at least one thin film device layer on a second substrate with a separable layer therebetween; and

irradiating the separable layer with light to cause a separation in at least one of the separable layers and at an interface so that the at least one thin film device layer on the second substrate is transferred to the first substrate.--

--22. (New) The method of transferring a three-dimensional device according to claim 21, the separation of the separable layer being caused by one of breakage and weakening of interatomic or intermolecular bonds in a material constituting the separable layer.--

--23. (New) The method of transferring a three-dimensional device according to claim 21, the separation of the separable layer being caused by evolution of gas from a material constituting the separable layer.--

--24. (New) The method of transferring a three-dimensional device according to claim 21, the light being a laser beam.--